

64-Kbit (8,192 x 8) Industrial High-Speed Parallel EEPROM with Page Write and Software Data Protection

AT28HC64B/AT28HC64BF



Features

- Fast Read Access Time: 70 ns (AT28HC64B) or 120 ns (AT28HC64BF)
- Automatic Page Write Operation:
 - Internal address and data latches for 64 bytes
- Fast Write Cycle Time:
 - Page Write cycle time: 10 ms maximum (AT28HC64B) or 2 ms maximum (AT28HC64BF)
 - 1 to 64-byte Page Write operation
- Low-Power Dissipation:
 - 40 mA active current
 - 100 μ A CMOS standby current
- Hardware and Software Data Protection
- $\overline{\text{DATA}}$ Polling and Toggle Bit for End of Write Detection
- High Reliability CMOS Technology:
 - Endurance: 100,000 cycles
 - Data retention: 10 years
- Single 5V \pm 10% Supply
- CMOS and TTL Compatible Inputs and Outputs
- JEDEC[®] Approved Byte-Wide Pinout
- Industrial Temperature Ranges
- Green RoHS-compliant Packaging Option Only

Packages

- 32-Lead PLCC, 28-Lead SOIC

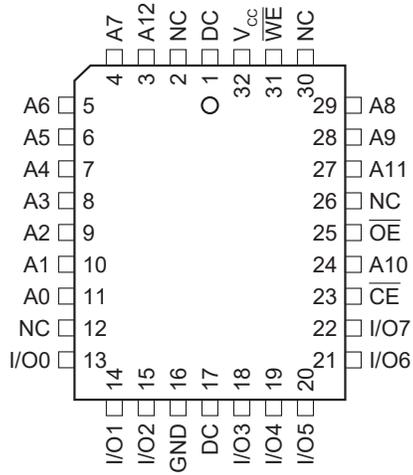
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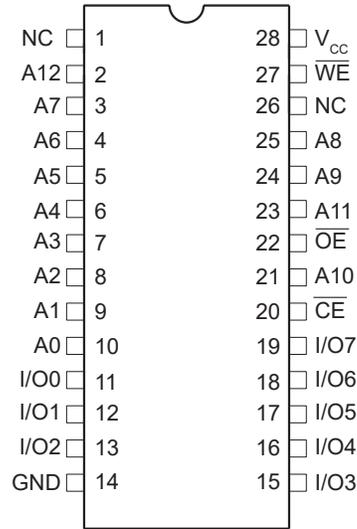
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1. Package Types (Not to Scale)

32-Lead PLCC
 Top View



28-Lead SOIC
 Top View



2. Pin Descriptions

The descriptions of the pins are listed in [Table 2-1](#).

Table 2-1. Pin Function Table

Name	32-Lead PLCC	28-Lead SOIC	Function
DC	1	—	Don't Connect
NC	2	1	No Connect
A12	3	2	Address
A7	4	3	Address
A6	5	4	Address
A5	6	5	Address
A4	7	6	Address
A3	8	7	Address
A2	9	8	Address
A1	10	9	Address
A0	11	10	Address
NC	12	—	No Connect
I/O0	13	11	Data Input/Output
I/O1	14	12	Data Input/Output
I/O2	15	13	Data Input/Output
GND	16	14	Ground
DC	17	—	Don't Connect
I/O3	18	15	Data Input/Output
I/O4	19	16	Data Input/Output
I/O5	20	17	Data Input/Output
I/O6	21	18	Data Input/Output
I/O7	22	19	Data Input/Output
\overline{CE}	23	20	Chip Enable
A10	24	21	Address
\overline{OE}	25	22	Output Enable
NC	26	—	No Connect
A11	27	23	Address
A9	28	24	Address
A8	29	25	Address
NC	30	26	No Connect
\overline{WE}	31	27	Write Enable
V _{CC}	32	28	Device Power Supply

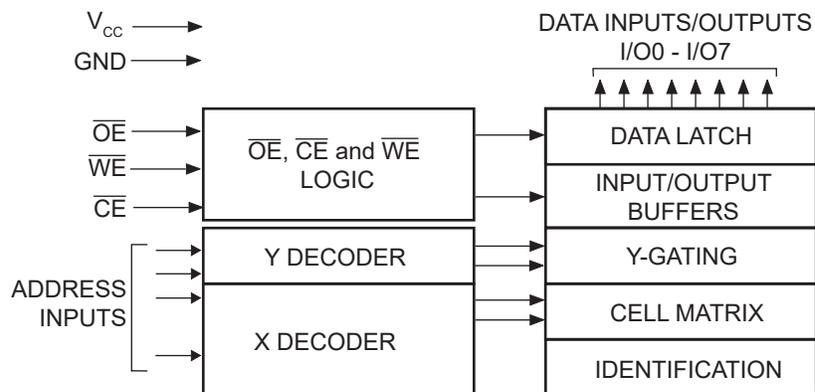
3. Description

The AT28HC64B/AT28HC64BF are high-performance Electrically Erasable and Programmable Read-Only Memory (EEPROM). Its 64-Kbit memory is organized as 8,192 words by 8 bits. Manufactured with Microchip's advanced nonvolatile CMOS technology, the AT28HC64B device offers access times as low as 70 ns while the AT28HC64BF offers access times of 120 ns, with power dissipation of just 220 mW. When the device is deselected, the CMOS standby current is less than 100 μ A.

The AT28HC64B/AT28HC64BF are accessed like Static RAM for the read or write cycle without the need for external components. The device contains a 64-byte page register to allow for writing up to 64 bytes simultaneously. During a write cycle, the addresses and one to 64 bytes of data are internally latched, freeing the address and data bus for other operations. Following the initiation of a write cycle, the device will automatically write the latched data using an internal control timer. The end of a write cycle can be detected by $\overline{\text{DATA}}$ Polling of I/O7. Once the end of a write cycle was detected, a new access for a read or write can begin.

The AT28HC64B/AT28HC64BF have additional features to ensure high quality and manufacturability. An optional software data protection mechanism is available to guard against inadvertent writes. The device also includes an extra 64 bytes of EEPROM for device identification or tracking.

3.1 Block Diagram



4. Electrical Characteristics

4.1 Absolute Maximum Ratings

Temperature under bias	-55°C to +125°C
Storage temperature	-65°C to +150°C
All input voltages (including NC pins) with respect to ground	-0.6V to +6.25V
All output voltages with respect to ground	-0.6V to $V_{CC} + 0.6V$
Voltage on OE and A9 with respect to ground	-0.6V to +13.5V

Note: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

4.2 DC and AC Operating Range

Table 4-1. DC and AC Operating Range

		AT28HC64B-70	AT28HC64B-90	AT28HC64B-12	AT28HC64BF-12
Operating Temperature (Case)	Industrial	-40°C to +85°C	-40°C to +85°C	-40°C to +85°C	-40°C to +85°C
V_{CC} Power Supply		5V ± 10%	5V ± 10%	5V ± 10%	5V ± 10%

4.3 DC Characteristics

Table 4-2. DC Characteristics

Parameter	Symbol	Minimum	Maximum	Units	Test Conditions
Input Load Current	I_{LI}	—	10	μA	$V_{IN} = 0V$ to $V_{CC} + 1V$
Output Leakage Current	I_{LO}	—	10	μA	$V_{IO} = 0V$ to V_{CC}
V_{CC} Standby Current CMOS	I_{SB1}	—	100	μA	$\overline{CE} = V_{CC} - 0.3V$ to $V_{CC} + 1V$
V_{CC} Standby Current CMOS	I_{SB2}	—	2	mA	$\overline{CE} = 2.0V$ to $V_{CC} + 1V$
V_{CC} Active Current	I_{CC}	—	40	mA	$f = 5MHz$; $I_{OUT} = 0mA$
Input Low Voltage	V_{IL}	—	0.8	V	
Input High Voltage	V_{IH}	2.0	—	V	
Output Low Voltage	V_{OL}	—	0.4	V	$I_{OL} = 2.1mA$
Output High Voltage	V_{OH}	2.4	—	V	$I_{OH} = -400\mu A$

4.4 Pin Capacitance

Table 4-3. Pin Capacitance^(1,2)

Symbol	Typical	Maximum	Units	Conditions
C_{IN}	4	6	pF	$V_{IN} = 0V$
C_{OUT}	8	12	pF	$V_{OUT} = 0V$

Notes:

1. This parameter is characterized but is not 100% tested in production.
2. $f = 1MHz$, $T_A = 25^\circ C$

5. Normalized I_{CC} Graphics

Figure 5-1. Normalized Supply Current vs. Temperature

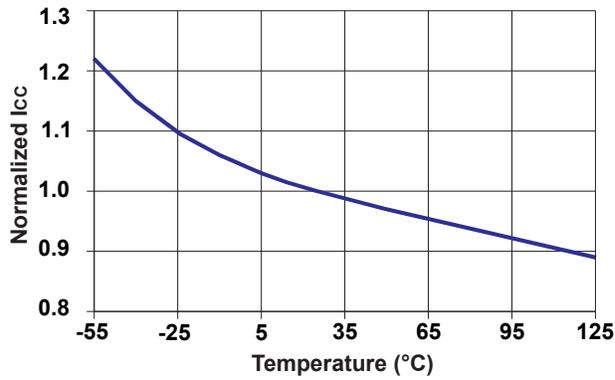


Figure 5-2. Normalized Supply Current vs. Address Frequency

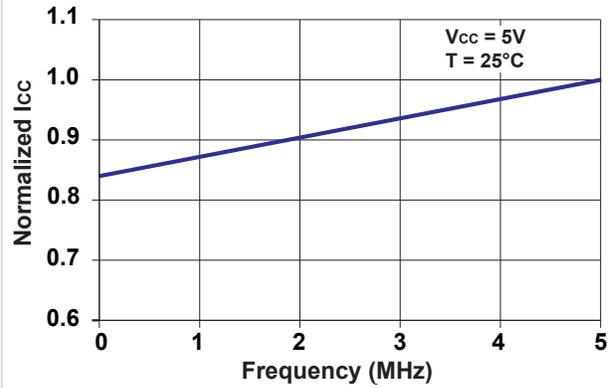
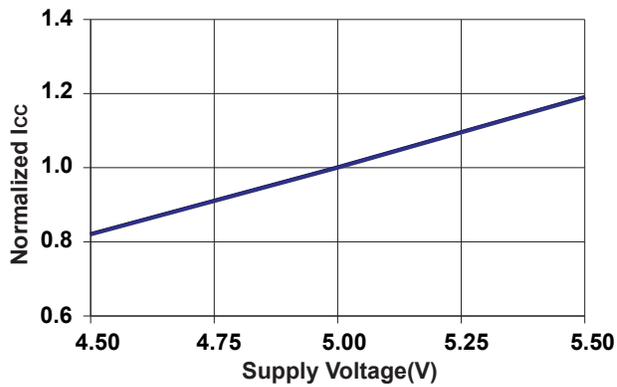


Figure 5-3. Normalized Supply Current vs. Supply Voltage



6. Device Operation

6.1 Read

The AT28HC64B/AT28HC64BF are accessed like Static RAM. When \overline{CE} and \overline{OE} are low and \overline{WE} is high, the data stored at the memory location determined by the address pins are asserted on the outputs. The outputs are put in the high-impedance state when either \overline{CE} or \overline{OE} is high. This dual-line control gives designers flexibility in preventing bus contention in their system.

6.2 Byte Write

A low pulse on the \overline{WE} or \overline{CE} input with \overline{CE} or \overline{WE} low (respectively) and \overline{OE} high initiates a write cycle. The address is latched on the falling edge of \overline{CE} or \overline{WE} , whichever occurs last. The data are latched by the first rising edge of \overline{CE} or \overline{WE} . Once a byte write is started, it will automatically time itself to completion. Once a programming operation is initiated and for the duration of t_{WC} , a read operation will effectively be a polling operation.

6.3 Page Write

The page write operation of the AT28HC64B/AT28HC64BF allows one to 64 bytes of data to be written into the device during a single internal programming period. A page write operation is initiated in the same manner as a byte write; the first byte written can then be followed by one to 63 additional bytes. Each successive byte must be written within 150 μs (t_{BLC}) of the previous byte. If the t_{BLC} limit is exceeded, the AT28HC64B/AT28HC64BF will cease accepting data and commence the internal programming operation. All bytes during a page write operation must reside on the same page as defined by the state of the A6-A12 inputs. For each \overline{WE} high-to-low transition during the page write operation, A6-A12 must be the same. The A0 to A5 inputs are used to specify which bytes within the page are to be written. The bytes may be loaded in any order and may be altered within the same load period. Only bytes which are specified for writing will be written; unnecessary cycling of other bytes within the page does not occur.

6.4 Data Polling

The AT28HC64B/AT28HC64BF feature \overline{DATA} Polling to indicate the end of a write cycle. During a byte or page write cycle, an attempted read of the last byte written will result in the complement of the written data to be presented on I/O7. Once the write cycle is completed, true data are valid on all outputs and the next write cycle may begin. \overline{DATA} Polling may begin at any time during the write cycle.

6.5 Toggle Bit

In addition to \overline{DATA} Polling, the AT28HC64B/AT28HC64BF provide another method for determining the end of a write cycle. During the write operation, successive attempts to read data from the device will result in I/O6 toggling between one and zero. Once the write is completed, I/O6 will stop toggling and valid data will be read. Reading the toggle bit may begin at any time during the write cycle.

6.6 Data Protection

If precautions are not taken, inadvertent writes may occur during transitions of the host system power supply. Microchip incorporated both hardware and software features that will protect the memory against inadvertent writes.

6.7 Hardware Data Protection

Hardware features protect against inadvertent writes to the AT28HC64B/AT28HC64BF in the following ways:

- V_{CC} sense – if V_{CC} is below 3.8V (typical), the write function is inhibited
- V_{CC} power-on delay – once V_{CC} has reached 3.8V, the device will automatically time out 5 ms (typical) before allowing a write
- Write inhibit – holding any one of \overline{OE} low, \overline{CE} high or \overline{WE} high inhibits write cycles
- Noise filter – pulses of less than 15 ns (typical) on the \overline{WE} or \overline{CE} inputs will not initiate a write cycle

6.8 Software Data Protection

A software-controlled data protection feature is available on the AT28HC64B/AT28HC64BF. When enabled, the software data protection (SDP) will prevent inadvertent writes. The SDP feature may be enabled or disabled by the user; the AT28HC64B/AT28HC64BF are shipped from Microchip with SDP disabled.

SDP is enabled when the user issues a series of three write commands in which three specific bytes of data are written to three specific addresses (see [Software Data Protection Enable Algorithm](#) and [Software Data Protection Disable Algorithm](#)). After writing the 3-byte command sequence and waiting t_{WC} , the entire AT28HC64B/AT28HC64BF will be protected against inadvertent writes.

It should be noted that even after SDP is enabled, the user may still perform a byte or page write to the AT28HC64B/AT28HC64BF by preceding the data to be written by the same 3-byte command sequence used to enable SDP.

Once set, SDP remains active unless the disable command sequence is issued. Power transitions do not disable SDP, and SDP protects the AT28HC64B/AT28HC64BF during power-up and power-down conditions. All command sequences must conform to the page write timing specifications. The data in the enable and disable command sequences are not actually written into the device; their addresses may still be written with user data in either a byte or page write operation.

After setting SDP, any attempt to write to the device without the 3-byte command sequence will start the internal write timers. No data will be written to the device. However, for the duration of t_{WC} , read operations will effectively be polling operations.

6.9 Device Identification

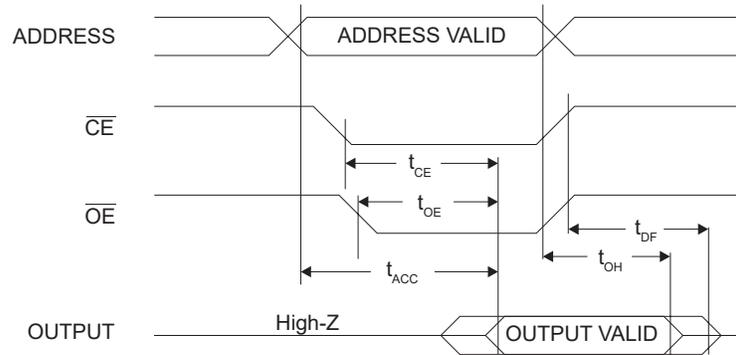
An extra 64 bytes of EEPROM memory are available to the user for device identification. By raising A9 to $12V \pm 0.5V$ and using address locations 1FC0H to 1FFFH, the additional bytes may be written to or read from in the same manner as the regular memory array.

6.10 AC Read Characteristics

Table 6-1. AC Read Characteristics

Parameter	Symbol	AT28HC64B-70		AT28HC64B-90		AT28HC64B-120		AT28HC64BF-120		Units
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
Address to Output Delay	t_{ACC}	—	70	—	90	—	120	—	120	ns
\overline{CE} to Output Delay	$t_{CE}^{(1)}$	—	70	—	90	—	120	—	120	ns
\overline{OE} to Output Delay	$t_{OE}^{(2)}$	0	35	0	40	0	50	0	50	ns
\overline{CE} or \overline{OE} to Output Float	$t_{DF}^{(3,4)}$	0	35	0	40	0	50	0	50	ns
Output Hold from \overline{OE} , \overline{CE} or Address, whichever occurred first	t_{OH}	0	—	0	—	0	—	0	—	ns

6.11 AC Read Waveforms^(1,2,3,4)



Notes:

1. \overline{CE} may be delayed up to $t_{ACC}-t_{CE}$ after the address transition without impact on t_{ACC} .
2. \overline{OE} may be delayed up to $t_{CE}-t_{OE}$ after the falling edge of \overline{CE} without impact on t_{CE} or by $t_{ACC}-t_{OE}$ after an address change without impact in t_{ACC} .
3. t_{DF} is specified from \overline{OE} or \overline{CE} , whichever occurs first ($C_L = 5$ pF).
4. This parameter is characterized and is not 100% tested.

6.12 Operating Modes

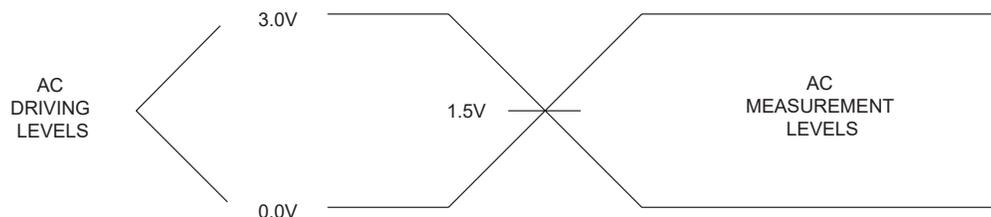
Table 6-2. Operating Modes

Mode	\overline{CE}	\overline{OE}	\overline{WE}	I/O
Read	V_{IL}	V_{IL}	V_{IH}	D_{OUT}
Write ⁽¹⁾	V_{IL}	V_{IH}	V_{IL}	D_{IN}
Standby/Write Inhibit	V_{IH}	X ⁽²⁾	X	High-Z
Write Inhibit	X	X	V_{IH}	—
Write Inhibit	X	V_{IL}	X	—
Output Disable	X	V_{IH}	X	High-Z
Chip Erase	V_{IL}	V_H ⁽³⁾	V_{IL}	High-Z

Notes:

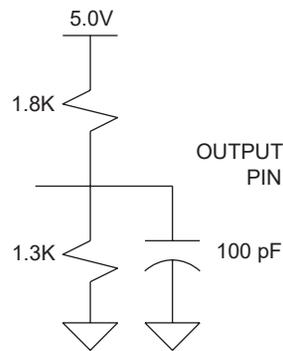
1. Refer to [AC Write Waveforms](#).
2. X can be V_{IL} or V_{IH} .
3. $V_H = 12.0\text{ V} \pm 0.5\text{ V}$

6.13 Input Test Waveforms and Measurement Level



Note: $t_R, t_F < 5$ ns.

6.14 Output Test Load



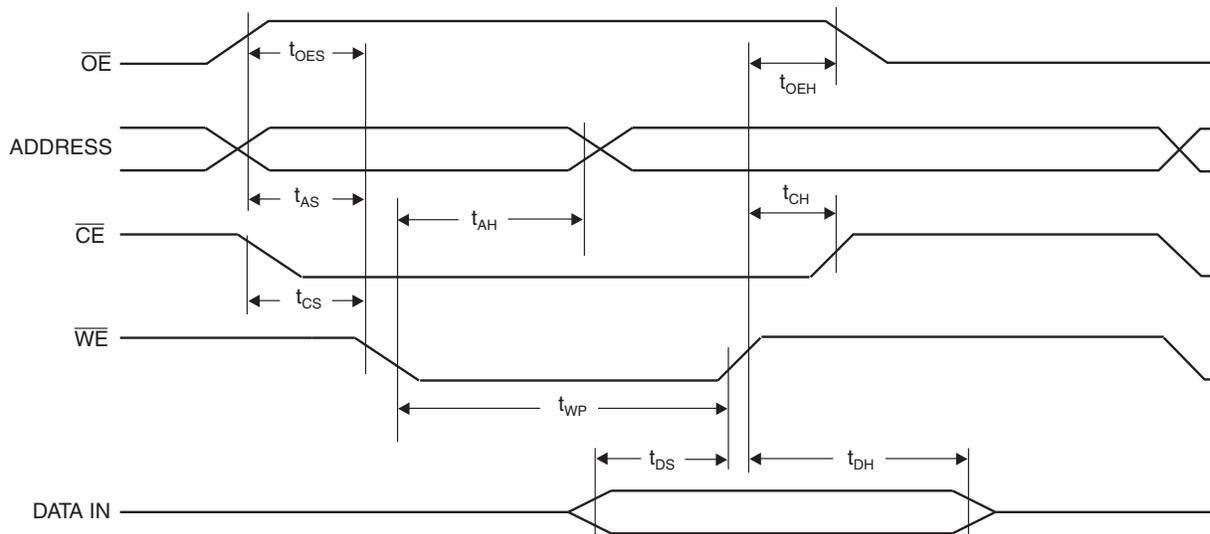
6.15 AC Write Characteristics

Table 6-3. AC Write Characteristics

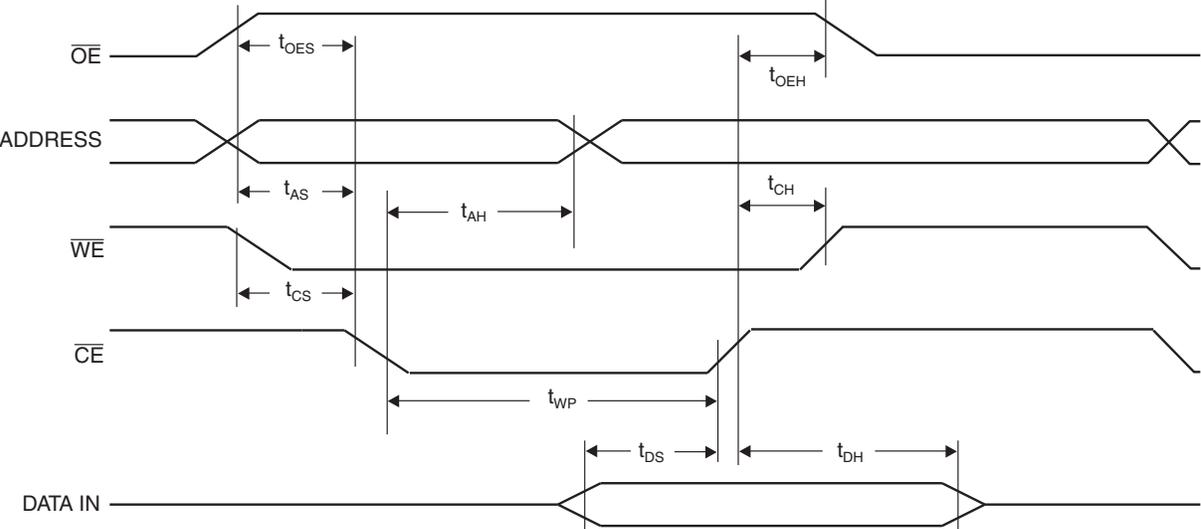
Parameter	Symbol	Minimum	Maximum	Units
Address, $\overline{\text{OE}}$ Setup Time	$t_{\text{AS}}, t_{\text{OES}}$	0	—	ns
Address Hold Time	t_{AH}	50	—	ns
Chip Select Setup Time	t_{CS}	0	—	ns
Chip Select Hold Time	t_{CH}	0	—	ns
Write Pulse Width ($\overline{\text{WE}}$ or $\overline{\text{CE}}$)	t_{WP}	100	—	ns
Data Setup Time	t_{DS}	50	—	ns
Data, $\overline{\text{OE}}$ Hold Time	$t_{\text{DH}}, t_{\text{OEH}}$	0	—	ns

6.16 AC Write Waveforms

6.16.1 $\overline{\text{WE}}$ Controlled



6.16.2 $\overline{\text{CE}}$ Controlled

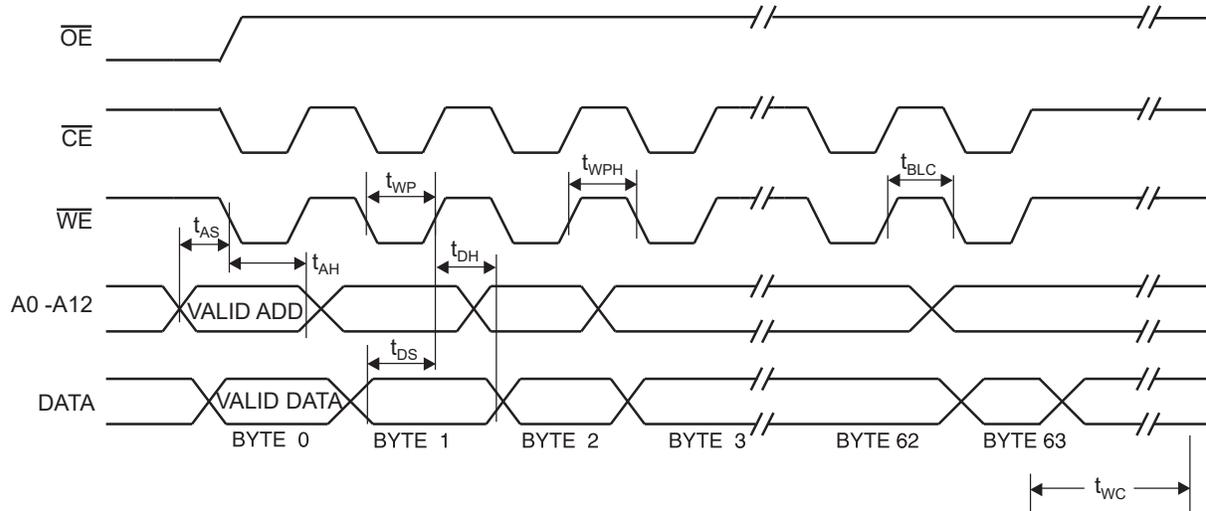


6.17 Page Mode Characteristics

Table 6-4. Page Mode Characteristics

Parameter	Symbol	Minimum	Maximum	Units
Write Cycle Time	t_{WC}	—	10	ms
		—	2	ms
Address Setup Time	t_{AS}	0	—	ns
Address Hold Time	t_{AH}	50	—	ns
Data Setup Time	t_{DS}	50	—	ns
Data Hold Time	t_{DH}	0	—	ns
Write Pulse Width	t_{WP}	100	—	ns
Byte Load Cycle Time	t_{BLC}	—	150	μ s
Write Pulse Width High	t_{WPH}	50	—	ns

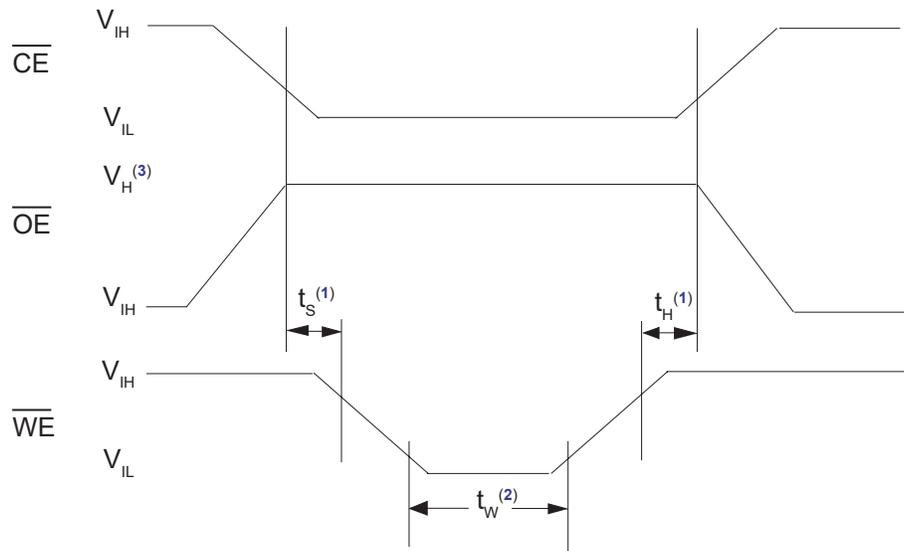
6.18 Page Mode Write Waveforms^(1,2)



Notes:

1. A6 through A12 must specify the same page address during each high-to-low transition of \overline{WE} (or \overline{CE}).
2. \overline{OE} must be high only when \overline{WE} and \overline{CE} are both low.

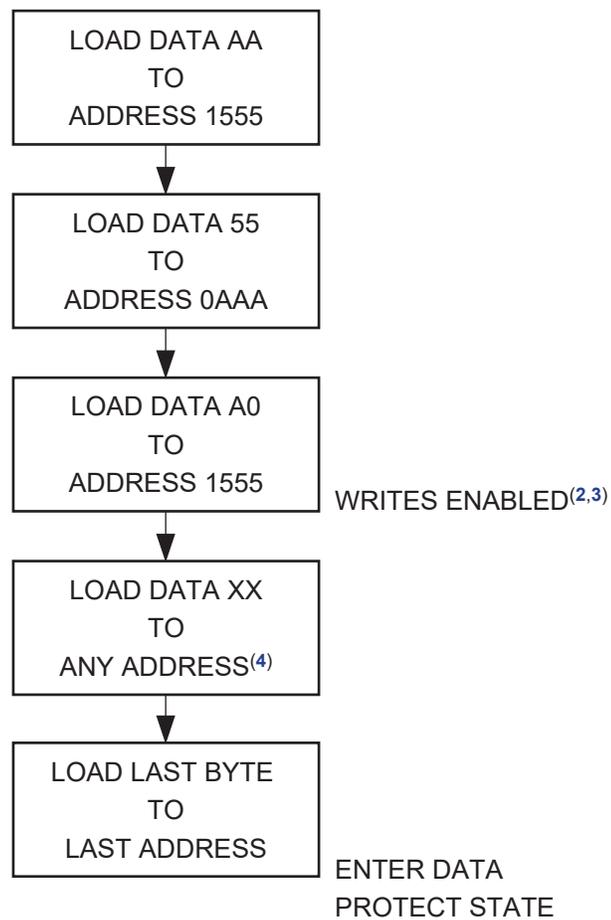
6.19 Chip Erase Waveforms



Notes:

1. $t_s = t_H = 5 \mu\text{sec}$ (minimum)
2. $t_w = 10 \text{ msec}$ (minimum)
3. $V_H = 12.0\text{V} \pm 0.5\text{V}$

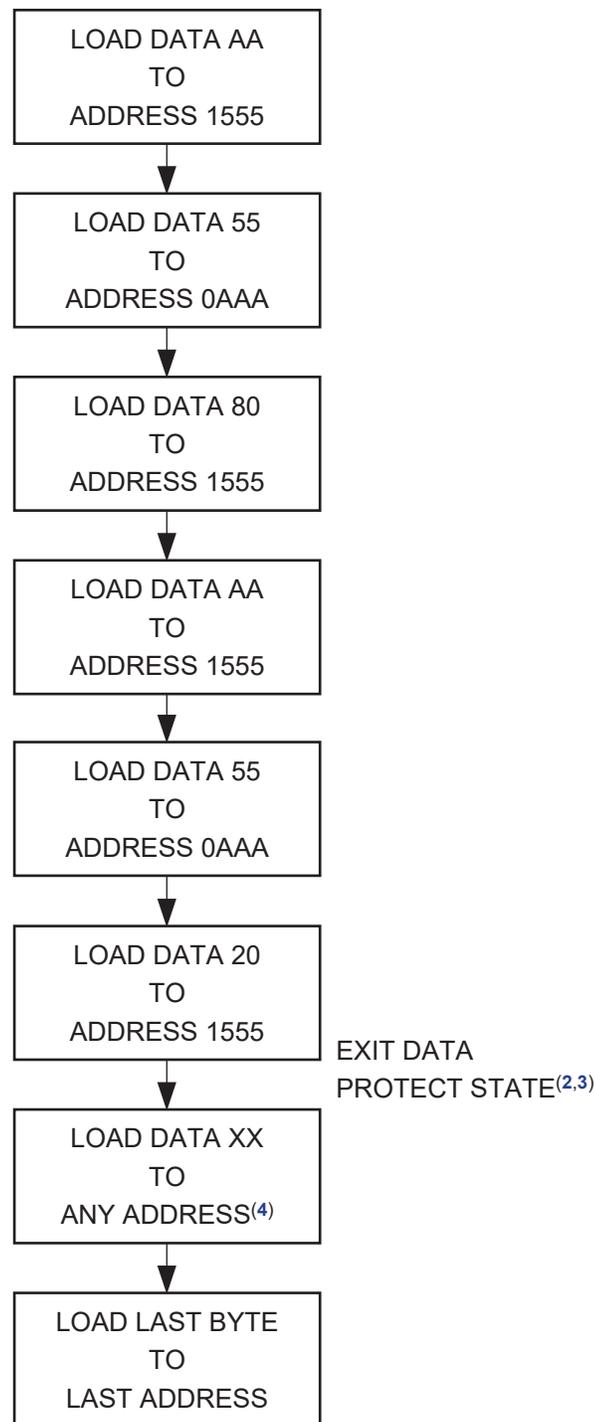
6.20 Software Data Protection Enable Algorithm⁽¹⁾



Notes:

1. Data format: I/O7-I/O0 (Hex); Address format: A12-A0 (Hex).
2. Write-Protect state will be activated at end of write even if no other data are loaded.
3. Write-Protect state will be deactivated at end of write period even if no other data are loaded.
4. One to 64 bytes of data are loaded.

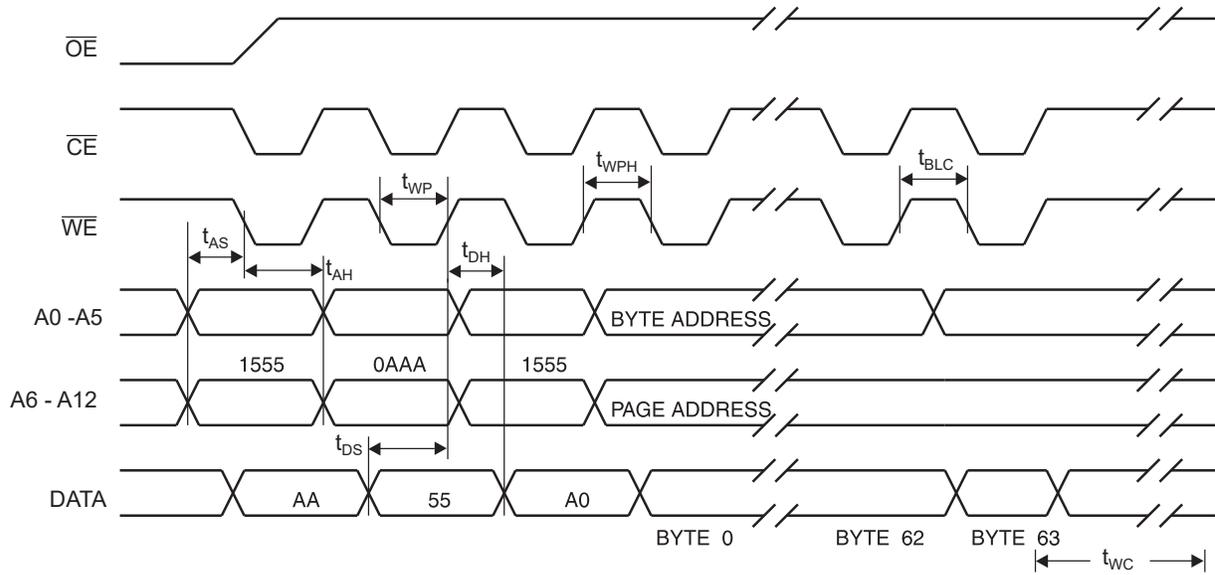
6.21 Software Data Protection Disable Algorithm⁽¹⁾



Notes:

1. Data format: I/O7-I/O0 (Hex); Address format: A12-A0 (Hex).
2. Write-Protect state will be activated at end of write period even if no other data are loaded.
3. Write-Protect state will be deactivated at end of write period even if no other data are loaded.
4. One to 64 bytes of data are loaded.

6.22 Software Protected Program Cycle Waveform^(1,2)



Notes:

1. A6-A12 must specify the same page address during each high-to-low transition of \overline{WE} (or \overline{CE}) after the software code has been entered.
2. \overline{OE} must be high only when \overline{WE} and \overline{CE} are both low.

6.23 Data Polling Characteristics⁽¹⁾

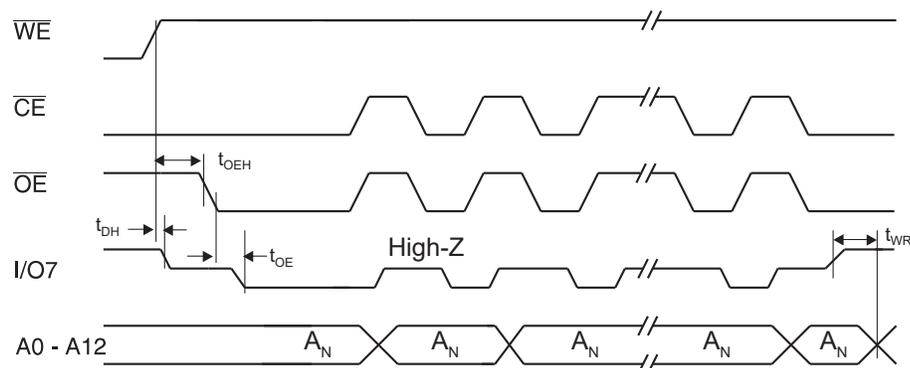
Table 6-5. Data Polling Characteristics

Parameter	Symbol	Minimum	Typical	Maximum	Units
Data Hold Time	t_{DH}	0	—	—	ns
\overline{OE} Hold Time	t_{OE}	0	—	—	ns
\overline{OE} to Output Delay ⁽²⁾	t_{OE}	—	—	—	ns
Write Recovery Time	t_{WR}	0	—	—	ns

Notes:

1. These parameters are characterized and not 100% tested.
2. See [AC Read Characteristics](#).

6.24 Data Polling Waveforms



6.25 Toggle Bit Characteristics⁽¹⁾

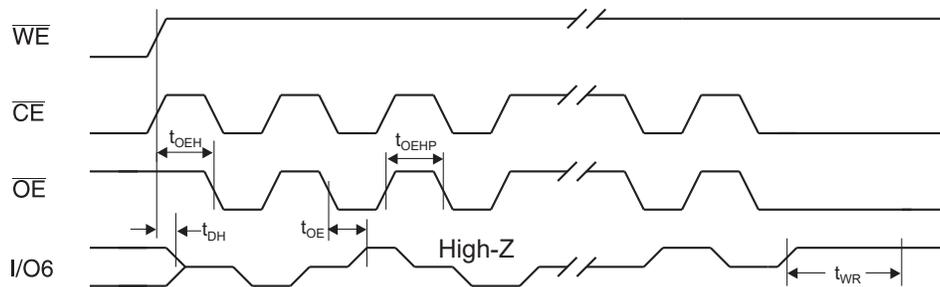
Table 6-6. Toggle Bit Characteristics

Parameter	Symbol	Minimum	Typical	Maximum	Units
Data Hold Time	t_{DH}	10	—	—	ns
\overline{OE} Hold Time	t_{OEH}	10	—	—	ns
\overline{OE} to Output Delay ⁽²⁾	t_{OE}	—	—	—	ns
\overline{OE} High Pulse	t_{OEHP}	150	—	—	ns
Write Recovery Time	t_{WR}	0	—	—	ns

Notes:

1. These parameters are characterized and not 100% tested.
2. See [AC Read Characteristics](#).

6.26 Toggle Bit Waveforms^(1,2,3)



Notes:

1. Toggling either \overline{OE} or \overline{CE} or both \overline{OE} and \overline{CE} will operate toggle bit.
2. Beginning and ending state of I/O6 will vary.
3. Any address location may be used but the address should not vary.

7. Packaging Information
7.1 AT28HC64B Package Marking Information

AT28HC64B: Package Marking Information

32-Lead PLCC

<p>Topside</p> <div style="border: 1px solid black; padding: 5px; margin: 5px auto; width: 80%;"> <p style="text-align: center;">●</p> <p style="text-align: center;">ATMEL AT28HC64B %%U-19803A YYWWNNN</p> </div>	<p>Backside</p> <div style="border: 1px solid black; width: 80%; height: 80%; margin: 5px auto;"></div>
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28-Lead SOIC

<p>Topside</p> <div style="border: 1px solid black; padding: 5px; margin: 5px auto; width: 80%;"> <p style="text-align: center;">ATMEL 19803A 28HC64B-%%U YYWWNNN</p> <p style="text-align: center;">●</p> </div>	<p>Backside</p> <div style="border: 1px solid black; width: 80%; height: 80%; margin: 5px auto;"></div>
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Note: No backside markings

		%% = Access Time
		70: 70 ns 90: 90 ns 12: 120 ns
		YYWWNNN: Lot Trace Code YY: Year, WW: Work Week NNN: Assembly Trace Code

7.2 AT28HC64BF Package Marking Information

AT28HC64BF: Package Marking Information

32-Lead PLCC

<p>Topside</p> <div style="border: 1px solid black; width: 80%; margin: 0 auto; padding: 5px; text-align: center;"> <p>●</p> <p>ATMEL AT28HC64BF 12U-19803A YYWWNNN</p> </div>	<p>Backside</p> <div style="border: 1px solid black; width: 80%; margin: 0 auto; height: 80px;"></div>
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28-Lead SOIC

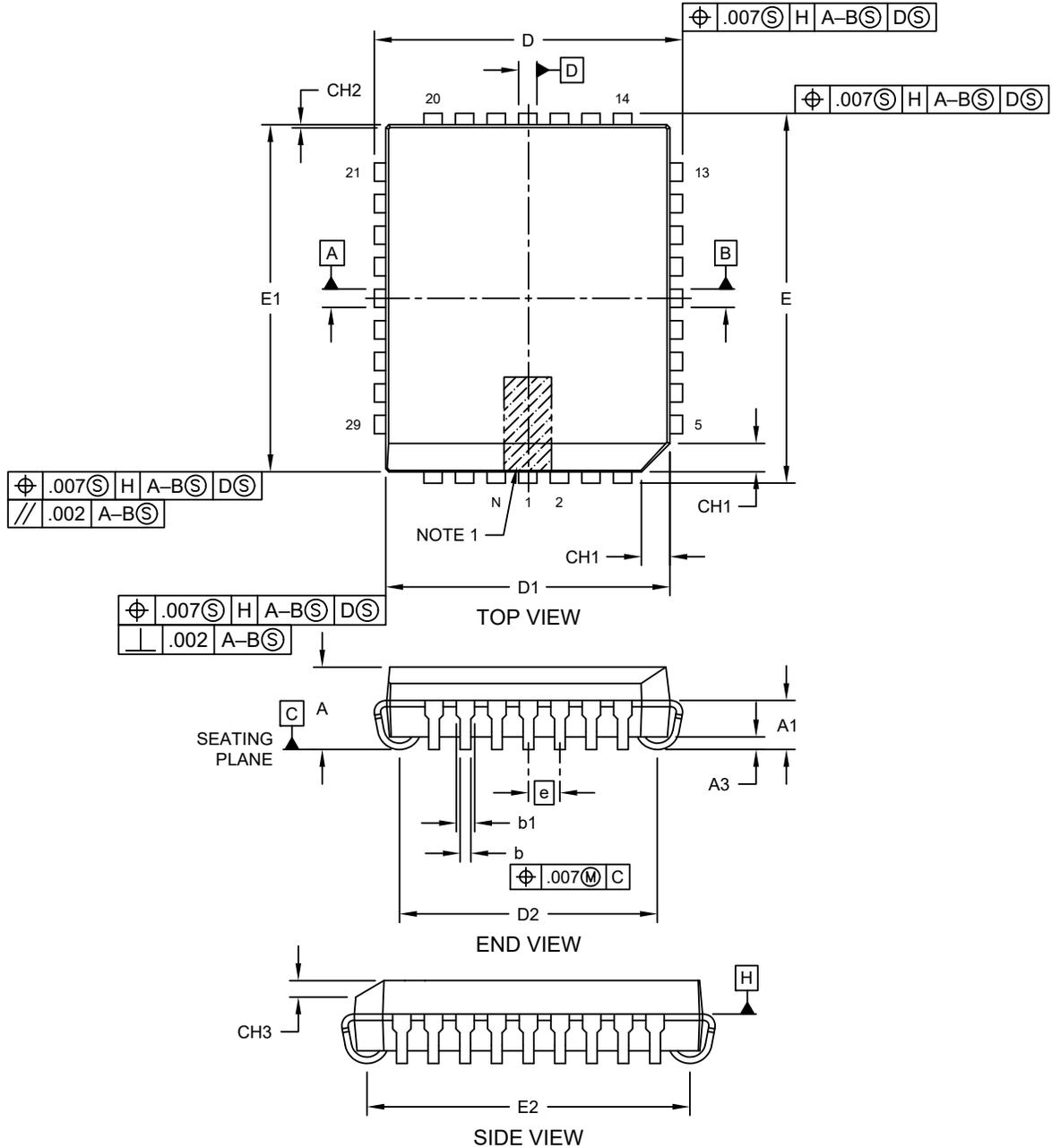
<p>Topside</p> <div style="border: 1px solid black; width: 80%; margin: 0 auto; padding: 5px; text-align: center;"> <p>ATMEL 19803A 28HC64BF-12U YYWWNNN</p> <p>●</p> </div>	<p>Backside</p> <div style="border: 1px solid black; width: 80%; margin: 0 auto; height: 80px;"></div>
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Note: No backside markings

Lot Trace Code		
YYWWNNN: Lot Trace Code YY: Year, WW: Work Week, NNN: Assembly Trace Code		

32-Lead Plastic Leaded Chip Carrier (L) - Rectangle [PLCC]

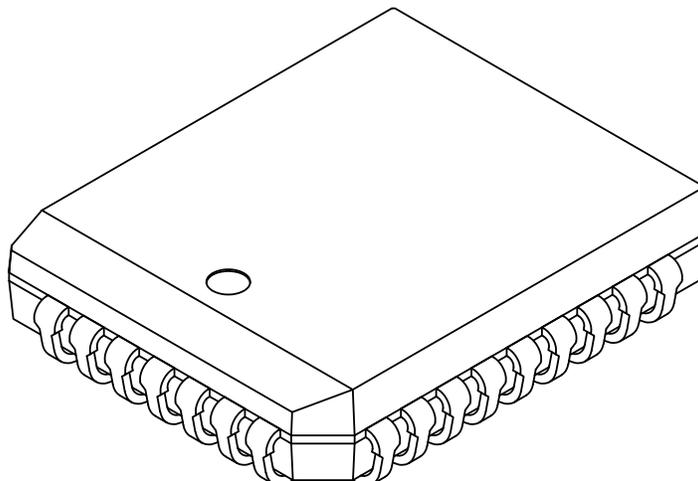
Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Microchip Technology Drawing C04-023 Rev C Sheet 1 of 2

32-Lead Plastic Leaded Chip Carrier (L) - Rectangle [PLCC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension Limits	Units	INCHES		
		MIN	NOM	MAX
Number of Pins	N	32		
Pitch	e	.050 BSC		
Pins along Length	ND	7		
Pins along Width	NE	9		
Overall Height	A	.125	.132	.140
Contact Height	A1	.060	.0775	.095
Standoff §	A3	.015	-	-
Corner Chamfer	CH1	.042	.045	.048
Chamfers	CH2	-	-	.020
Side Chamfer Height	CH3	.023	.026	.029
Overall Length	D	.485	.490	.495
Overall Width	E	.585	.590	.595
Molded Package Length	D1	.447	.450	.453
Molded Package Width	E1	.547	.550	.553
Footprint Length	D2	.376	.411	.446
Footprint Width	E2	.476	.511	.546
Lead Thickness	c	.008	.010	.013
Upper Lead Width	b1	.026	.029	.032
Lower Lead Width	b	.013	.017	.021

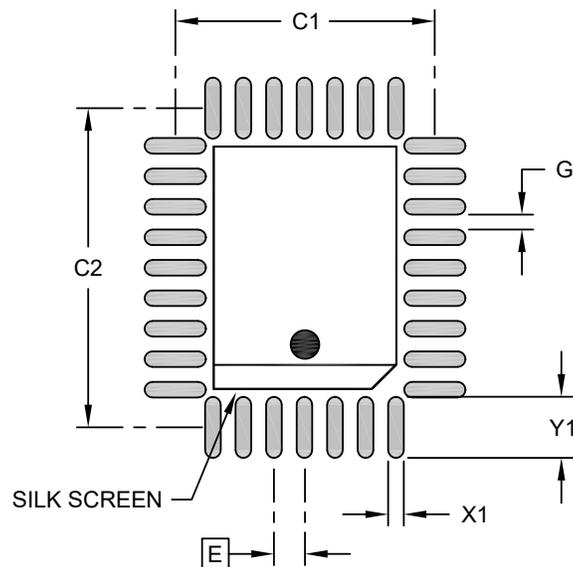
Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-023 Rev C Sheet 2 of 2

32-Lead Plastic Leaded Chip Carrier (L) - Rectangle [PLCC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Dimension Limits	Units	INCHES		
		MIN	NOM	MAX
Contact Pitch	E	.050 BSC		
Contact Pad Spacing	C1		.425	
Contact Pad Spacing	C2		.524	
Contact Pad Width (X32)	X1			.026
Contact Pad Length (X32)	Y1			.100
Contact Pad to Center Pad (X28)	G	.008		

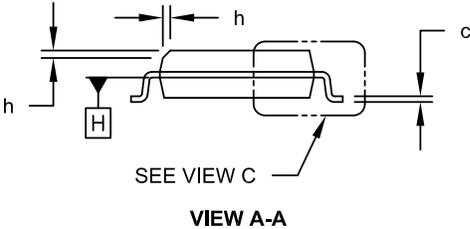
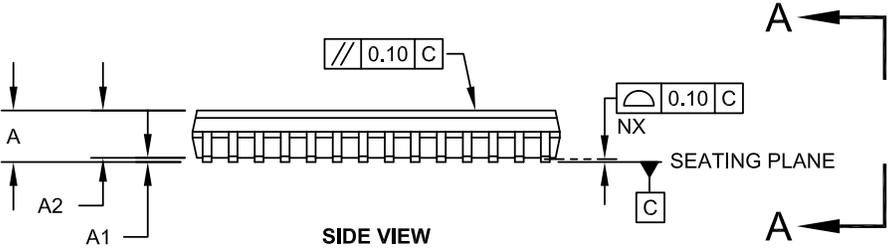
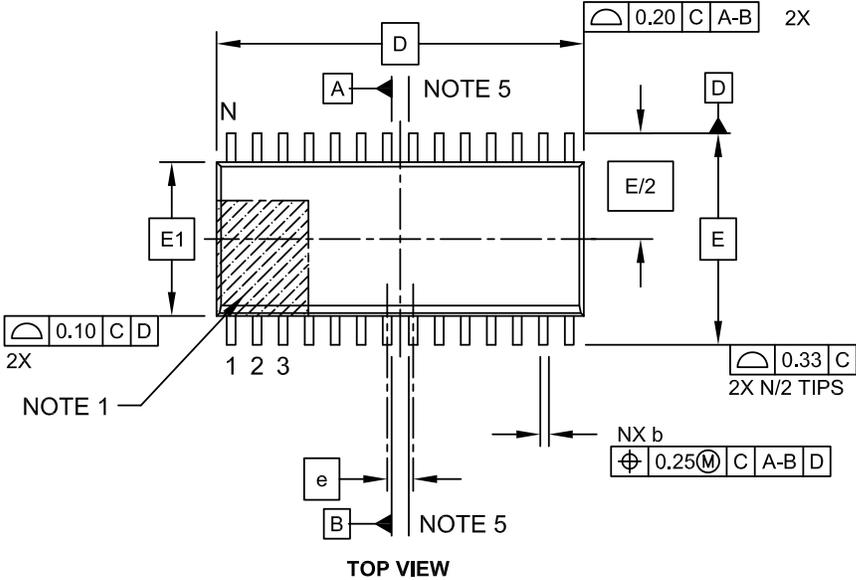
Notes:

- Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
- For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process

Microchip Technology Drawing C04-2023 Rev C

28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

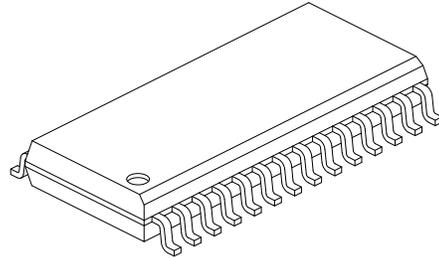
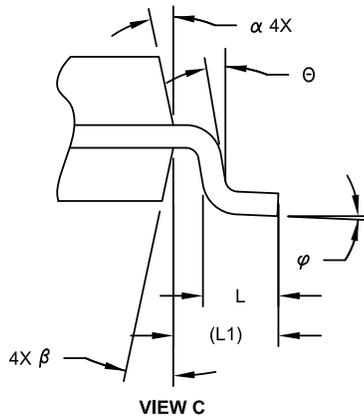
Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Microchip Technology Drawing C04-052C Sheet 1 of 2

28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Number of Pins	N	28		
Pitch	e	1.27 BSC		
Overall Height	A	-	-	2.65
Molded Package Thickness	A2	2.05	-	-
Standoff §	A1	0.10	-	0.30
Overall Width	E	10.30 BSC		
Molded Package Width	E1	7.50 BSC		
Overall Length	D	17.90 BSC		
Chamfer (Optional)	h	0.25	-	0.75
Foot Length	L	0.40	-	1.27
Footprint	L1	1.40 REF		
Lead Angle	θ	0°	-	-
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.18	-	0.33
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

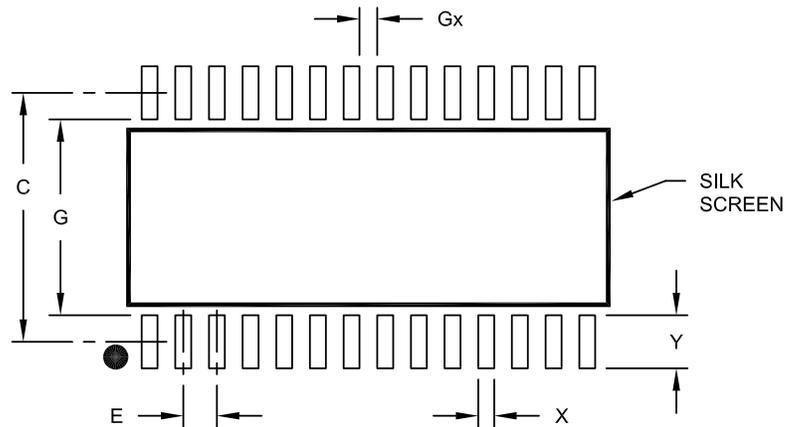
Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- § Significant Characteristic
- Dimension D does not include mold flash, protrusions or gate burrs, which shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion, which shall not exceed 0.25 mm per side.
- Dimensioning and tolerancing per ASME Y14.5M
 BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 REF: Reference Dimension, usually without tolerance, for information purposes only.
- Datums A & B to be determined at Datum H.

Microchip Technology Drawing C04-052C Sheet 2 of 2

28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E	1.27 BSC		
Contact Pad Spacing	C		9.40	
Contact Pad Width (X28)	X			0.60
Contact Pad Length (X28)	Y			2.00
Distance Between Pads	Gx	0.67		
Distance Between Pads	G	7.40		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2052A

8. Revision History

Revision B (September 2023)

Incorporated global edits and removed 28-Lead TSOP device package references due to EOL of that device package. Updated 32-Lead PLCC drawings to latest revision (no changes to form, fit or function).

Revision A (December 2020)

Updated to the Microchip template. Microchip DS20006473 replaces Atmel documents 0274 and 3648. Added updated Part Markings to include new trace code format. Replaced Atmel 32J and 28S package drawings with Microchip P3X and N3X package drawings.

Atmel Document 3648 Revision B (April 2009)

No Revision History section in Atmel data sheet at that time.

Atmel Document 0274 Revision L (Feb 2009)

No Revision History section in Atmel data sheet at that time.

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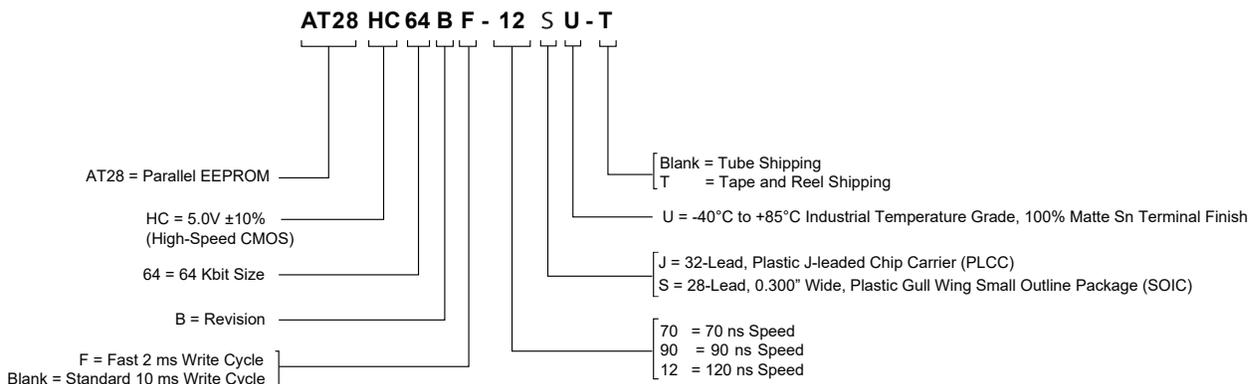
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- Local Sales Office
- Embedded Solutions Engineer (ESE)
- Technical Support

Customers should contact their distributor, representative or ESE for support. Local sales offices are also available to help customers. A listing of sales offices and locations is included in this document.

Technical support is available through the website at: www.microchip.com/support

Product Identification System

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.



Examples

Table 9-1. Ordering Information

Ordering Code	Package Drawing Code	Package Option	t _{ACC} (ns)	Quantity	Operating Range
AT28HC64B-70JU	L	J	70	32 Tube	Industrial Temperature (-40°C to +85°C)
AT28HC64B-70JU-T				750 Reel	
AT28HC64B-70SU	SO	S		27 Tube	
AT28HC64B-70SU-T				1,000 Reel	
AT28HC64B-90JU	L	J	90	32 Tube	
AT28HC64B-90JU-T				750 Reel	
AT28HC64B-90SU	SO	S		27 Tube	
AT28HC64B-90SU-T				1,000 Reel	
AT28HC64B-12JU	L	J	120	32 Tube	
AT28HC64BF-12JU				32 Tube	
AT28HC64B-12JU-T				750 Reel	
AT28HC64BF-12JU-T				750 Reel	
AT28HC64B-12SU	SO	S		27 Tube	
AT28HC64BF-12SU				27 Tube	
AT28HC64B-12SU-T				1,000 Reel	
AT28HC64BF-12SU-T				1,000 Reel	
AT28HC64B-DWF	Contact Microchip Sales for Die Sales				
AT28HC64BF-DWF					

Note: Contact Microchip Sales.

Package Types	
J	28-Lead, 0.300" Wide, Plastic Gull Wing Small Outline (SOIC)
S	32-Lead, Plastic J-leaded Chip Carrier (PLCC)
DWF	Die in Wafer Form shipped in 6-inch round jars

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